



# RI-TRP-R9VS, RI-TRP-W9VS

SCBS876-NOVEMBER 2008

# **MOUNT-ON-METAL TRANSPONDER**

#### **FEATURES**

www.ti.com

- Best in Class Performance Through Patented HDX Technology
- Patented Transponder Tuning Provides Stable and High Read/Write Performance
- 64-Bit Read-Only Memory (RI-TRP-R9VS) 80-Bit Read-Write Memory (RI-TRP-W9VS)
- Insensitive to Almost All Non-Metallic Materials

### **APPLICATIONS**

- Waste Management
- Asset Management
- Container Tracking
- Vehicle Identification
- Access Control

## **DESCRIPTION**

Texas Instruments mount-on-metal transponder provides superior performance and operates at a resonance frequency of 134.2 kHz. Texas Instruments LF transponders are manufactured with TI's patented tuning process to provide consistent read and write performance. Prior to delivery, the transponders undergo complete functional and parametric testing, in order to provide the high quality customers have come to expect from TI. The transponder is well suited for usage in a broad range of applications including, but not limited to, access control, vehicle identification, container tracking, asset management, and waste management applications.

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

#### NOTE:

For more information, contact the sales office or distributor nearest you. This contact information can be found on our web site at <a href="http://www.ti.com/rfid">http://www.ti.com/rfid</a>.



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## **ABSOLUTE MAXIMUM RATINGS**

over operating free-air temperature range (unless otherwise noted)

	RI-TRP-R9VS, RI-TRP-W9VS					
Operating Temperature	-25 to 70°C					
Storage Temperature	-25 to 85°C					

## **OPERATING CHARACTERISTICS**

over operating free-air temperature range (unless otherwise noted)

	RI-TRP-R9VS	RI-TRP-W9VS					
Functionality	Read only	Read/write					
Memory (Bits)	64	80					
Memory (Pages)	1	1					
Operating Frequency	134.2 kHz						
Modulation	FSK (frequency shift keying) 134.2 kHz / 123.2 kHz						
Transmission Principle	HDX (half duplex)						
Power Source	Powered from the reader signal						
Typical Reading Range	≤120 cm <sup>(1)</sup>						
Typical Programming Range	_	30% of typical reading range					
Typical Reading Time	70 ms						
Typical Programming Time	_	309 ms					
Typical Programming Cycles	_	100,000					
Case Material	Polypropylene, black						
Protection Class	IP 67						
Mounting	With screws or rivets on aluminum, iron, or steel						
EMC	Programmed code is not affected by normal electromagnetic interference or X-rays						
Signal Penetration	Transponder can be read through virtually all non-metallic material						
Mechanical Shock	IEC 68-2-27, Test Ea; 200 g, half sine, 3 ms, 3 axes, 6 shocks per axis						
Vibration	IEC 68-2-6, Test Fc; 20 g, 20 - 500 Hz, 3 axes, 10 cycles per axis						
Dimensions	102 mm ± 1 mm × 36 mm ± 1 mm × 16.5 mm ± 1 mm						
Weight	43 g						

<sup>(1)</sup> Depending on RF regulation in country of use, the reader antenna configuration used, and the environmental conditions.

Submit Documentation Feedback



# PACKAGE OPTION ADDENDUM

1-May-2018

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package	Pins Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing	Qty	(2)	(6)	(3)		(4/5)	
RI-TRP-W9VS-30	OBSOLETE	RFIDP	TEJ	0	TBD	Call TI	Call TI	-25 to 70		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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